

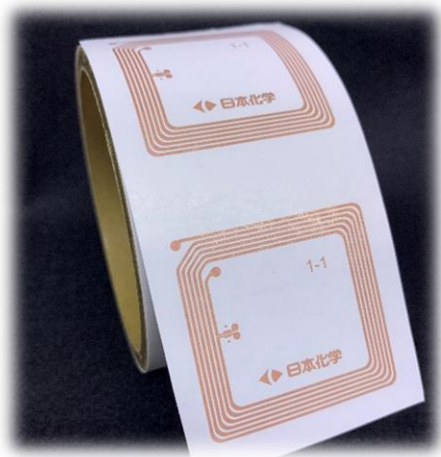
## Copper oxide paste for photo sintering

**Curelight®**

Curelight® can be formed on low heat resistant substrates

**Features**

- ✓ Rapid sintering under the air atmosphere
- ✓ Low volume resistivity
- ✓ Fine line printing
- ✓ Good adhesion on substrate
- ✓ Long shelf life



RFID tag formed by Photo sintering

**Properties of Curelight®**

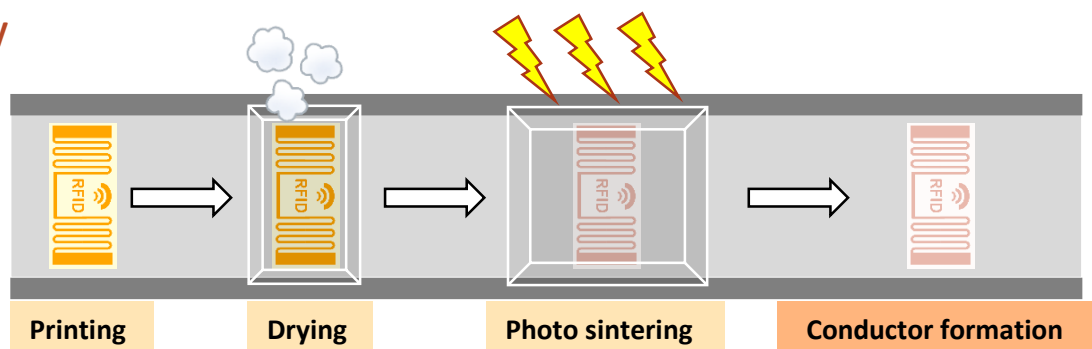
Conductive particle	Copper oxide (Cu <sub>2</sub> O)
Cu <sub>2</sub> O Content	40 – 80 wt.%
Solvent	Organic Solvent
Particle size	100 - 200 nm

**Properties of photo sintering Cu film (After press)**

Volume resistivity	< 20 μΩ · cm
Film thickness	< 10 μm
Applicable substrate	PET, Paper, PI
Adhesive tape peel test	Pass

**Photo sintering Process**

- ✓ Formed on low heat resistant substrates
- ✓ High productivity
- ✓ Space saving

**Application**

RFID Antenna, electromagnetic wave shield, Sensor, Touch panel, FPC etc.